# **PRODUCT SPECIFICATION**

# CS2004B-D-BSXTSWN-100

V1.0

June 24, 2010

Easterntronic LCD Group

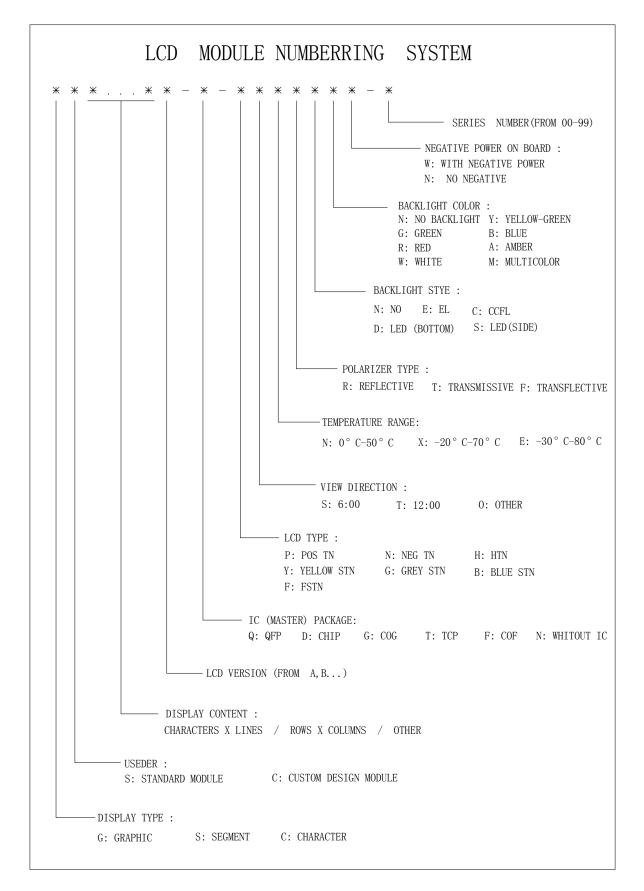
<b>REVISION RECORD</b>
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DESCRIPTION	DATE
	June 24, 2010
	DESCRIPTION

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# **1. LCD MODULE NUMBERING SYSTEM**





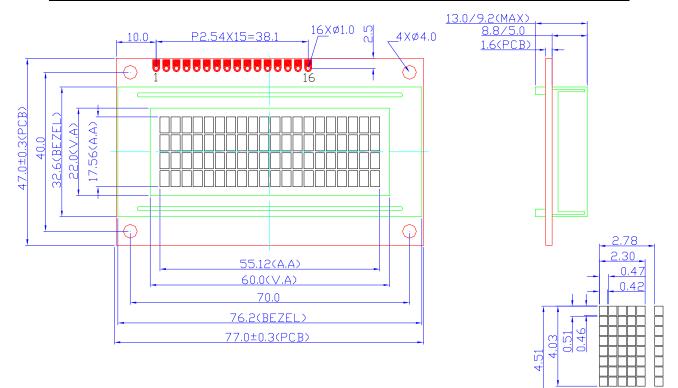
# 2. TYPE NUMBER AND DESCRIPTION

Type Number	:	CS2004B-D-BSXTSWN-100
Description	:	20 Characters X 4 lines
LCD Panel	:	Blue- STN, Negative, Transmissive
Viewing angle	:	6Н
Duty and Bias	:	1/16 duty; 1/5 bias
Logic Voltage	:	5.0V
Operating Temperature	e :	-20°C70°C
Storage Temperature	:	-30°C80°C
Controller	:	ST7066U-0A or Equivalent
IC package	:	Bonding
BackLight Type	:	Side, white



ITEM	STANDARD VALUE	UNIT			
CHARACTER NUMBER	20 CHARATERS X 4 LINES				
MODULE DIMENSION	77.0 (W) X 47.0 (H) X 13.0 (H)	mm			
DISPLAY AREA	60.0(W) X 22.0 (H)	mm			
CHARACTER FORMAT	5 X 7 DOTS WITH CURSOR				
CHARACTER SIZE	2.3(W) X 4.03(H)	mm			
CHARACTER PITCH	2.78(W) X 4.51(H)	mm			
DOT SIZE	0.42 (W) X 0.46 (H)	mm			
DOT PITCH	0.47 (W) X 0.51 (H)	mm			
APP APPROX WEIGHT	70	g			
LCD TYPE	Blue- STN, Negative, Transmissive				
DUTY AND BIAS	1/16 DUTY ;1/5 BIAS				
VIEWING DIRECTION	6Н				
BACKLIGHT	Side, White				

#### 3. MECHANICAL SPECIFICATIONS:



\*Non-specificed tolerance is +/-0.2mm

e

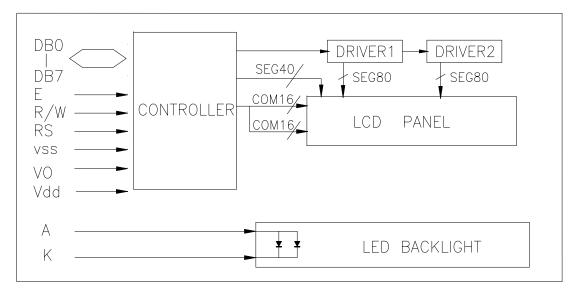
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## 4. ELECTRICAL BLOCK DIAGRAM

#### 4.1 Pin Definition

PIN	SYMBOL	FUNCTION						
1	Vss	Power Supply(GND)						
2	Vdd	Power Supply(+5.0V)						
3	Vo	Contrast Adjust						
4	RS	Instruction/Data Register Select						
5	R/W	Data Bus Line						
6	Е	Enable Signal						
7-14	DB0-DB7	Data Bus Line						
15	А	Power Supply for LED B/L(+)						
16	K	Power Supply for LED B/L(-)						

4.2 Electrical Block Diagram



#### Display Character Address Code 4.3

DISPLAY POSITION	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20
DDRAM	00																			13
	40	41	42	43	44	45	46	47	48	49	4A	4B	4C	4D	4E	4F	50	51	52	53
ADDRESS	14	15	16	17	18	19	1A	1B	1C	1D	1E	1F	20	21	22	23	24	25	26	27
	54	55	56	57	58	59	5A	5B	5C	5D	5E	5F	60	61	62	63	64	65	66	67

### 5. ABSOLUTE MAXIMUM RATINGS

#### CONDITI **SYMBOL** MIN MAX UNIT **ITEM** ON Supply Voltage Vdd - VssV 0 7.0 \_ (Logic) Supply Voltage Vdd - V00 11.5 V \_ (LCD Drive) Input Voltage Vi -0.3 Vdd +0.3 V \_

### 5.1 Electrical Maximum Ratings (Ta=25deg C)

#### 5.2 Environmental Conditions

ITEM	SYMBOL	CONDITION	MIN	MAX	UNIT
Operating Temp	Topr	-	-20	70	deg C
Storage Temp	Ttsg	-	-30	80	deg C

### 6. ELECTRICAL SPECIFICATIONS

6.1 Electrical Characteristics at Ta=25 deg C, Vdd = 5.0V + / - 5%

	SYMB	CONDITIO	MI			
ITEM	OL	N	N	TYP	MAX	UNIT
Supply Voltage (logic)	Vdd-Vs s	-	-	5.0	-	V
Supply Voltage (LCD)	Vdd-V0	Vdd = 3.3V	4.6	4.8	5.0	V
Input signal voltage	V-ih	"H" level	2.2	-	Vdd	V
(for E, DB0-7,R/W,RS)	V-il	"L" level	0	-	0.6	V
Supply Current (logic)	Icc	-	0.9	1	1.2	mA
Supply Current (LCD)	Io	-	0.15	0.22	0.27	mA
Supply Voltage (LED)	V-LED	-	2.8	3.1	3.3	V
Supply Current (LED)	If	-	-	30	45	mA
*Peak forward current(B/L)	lfp	I mseo pulse 10% Duty Cycle	-	-	120	mA
*Power dissipation(B/L)	Pd		-	-	124	mW

\*For operation above 25°C, the If  $If_RPd$  must be derated, the current derating is -0.62 mA/°C for DC drive and -1.72 mA/°C for pulse drive, the power dissipation is -1.92 mW /°C. The Blacklight working current must not more than 60% of the Ifmax or Ifpmax according to the working temperature.



6.2 Timing Specifications at Ta = 25 deg C, Vdd =5.0V + -10%, Vss =0V

# 6.2.1Write mode

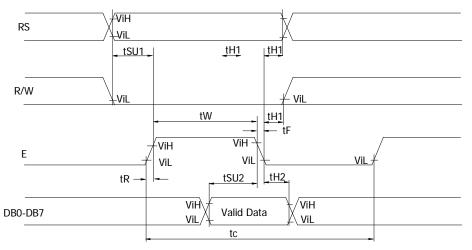
ITEM	SYMBOL	MIN	MAX	UNIT
E cycle time	tc	1200	-	ns
E rise time	tR	-	25	ns
E fall time	tF	-	25	ns
E-pulse width (H, L)	tw	140	-	ns
R/W and RS set-up time	tsul	40	-	ns
R/W and RS hold time	tH1	10	-	ns
Data set-up time	tsu2	40	_	ns
Data hold time	tH2	10	_	ns

6.2.2 Read mode

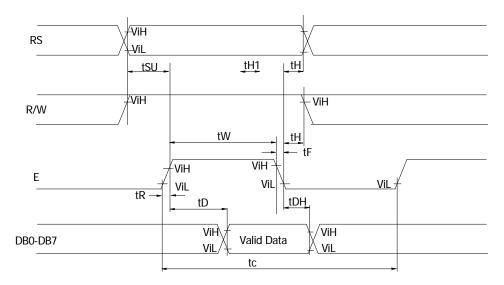
ITEM	SYMBOL	MIN	MAX	UNIT
E cycle time	tc	1200	-	ns
E rise time	tR	-	25	ns
E fall time	tF	-	25	ns
E-pulse width (H, L)	tw	140	-	ns
R/W and RS set-up time	tsu	0	-	ns
R/W and RS hold time	tH	10	-	ns
Data output delay	tD	_	120	ns
Data hold time	tDH	10	_	ns

# 6.2.3 TIMING DIAGRAM

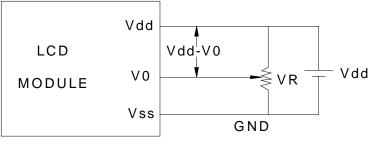
#### WRITE MODE TIMING DIAGRAM



READ MODE TIMING DIAGRAM



#### 7. POWER SUPPLY FOR LCD MODULE



Vdd - V0: LCD Driving Voltage VR: 10K - 20K

### 8. ELECTRO-OPTICAL CHARACTERISTIC

ITEM	SYMB OL	CONDI TION	MIN.	ТҮР.	MAX.	UNIT	REF.	
Contrast	CR	25℃		12			Note1	
Rise Time	tr	25℃		160	240	ms	Note2	
Fall Time	tf	25℃		100	150	ms	note 2	
Viewing Angle	θ 1- θ 2	25℃			60	DEC	Note 2	
Viewing Angle	Ø1, Ø2	23 C	-40		40	DEG	Note 3	
Frame	Ff	25℃		61		Цą	noto 2	
Frequency	ГІ	23 C		64		Hz	note 2	

#### Note(1): Contrast ratio is defined under the following condition:

CR= brightness of selected condition

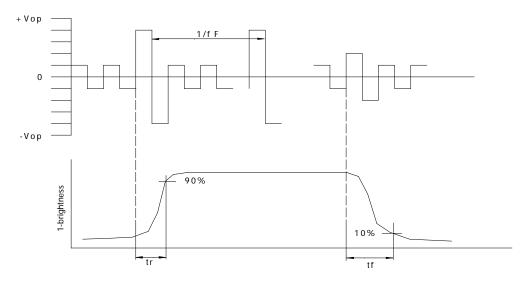
brightness of non-selected condition



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- (a). Temperature-----25C
- (b). Frame Frequency-----64Hz
- (c). Viewing angle-----  $\theta = 0, \emptyset = 0$
- (d). Operating Voltage---4.8V

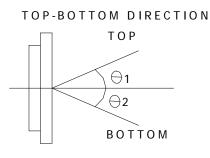
#### Note(2): definition of response time:

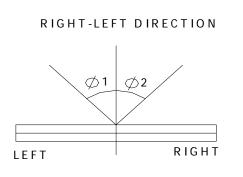


# **Condition:**

- (a). Temperature-----25C
- (b). Frame Frequency-----64Hz
- (c). Viewing angle-----  $\theta = 0, \emptyset = 0$
- (d). Operating Voltage---4.8V

### Note(3): definition of view angle:





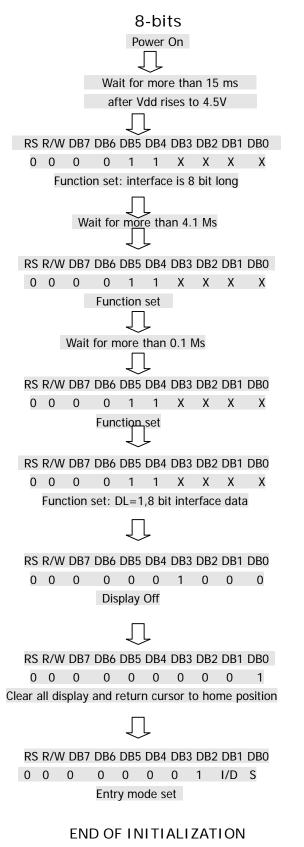


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# 9. INSTRUCTION TABLE

Function	R	R	D	D	D		D		D	D	Description	Execu
							В				•	Time*
			7	6	5	4	3	2	1	0		(Max)
Clear	0	0	_	_	_	-	-	_	_	_	Clears entire display and returns the cursor to	
Display											home position (address 0)	
Return	0	0	0	0	0	0	0	0	1	Х	Return the cursor to the home position. DD RAM	1.64mS
Home											contents remain unchanged. Set DD RAM address	
											to zero.	
Entry	0	0	0	0	0	0	0	1	1	S	Set cursor moving direction and enable the	40 µ S
mode									1		shift of the display. These operations are	
set									D		performed during data write/read of DD RAM/CG	
											RAM. 1/D=1: increment; 1/D=0: decrement; S=1:	
											whole display shift when data is written.	
Display	0	0	0	0	0	0	1	D	С	В	Set display (D),cursor(C) and blinking of cursor(B)	40 µ S
ON/OFF											ON/OFF. D=1:display ON; D=0: display OFF.	
control											C=1:Cursor ON; C=0:cursot OFF. B=1:Blink ON;	
											B=0, Blink OFF.	
Cursor or	0	0	0	0	0	1	S	R	Х	Х	Move the cursor and shift the display without	40 µ S
Display							1				changing DDRAM contents. S/C=1: Display Shift;	
shift							С	L			S/C=0:Cursor move. R/L=1:shift to right;	
											R/L=0:shift to left.	
Function	0	0	0	0	1	D	N	F	Х	Х	Set interface data length (DL), number of display	40 µ S
Set						L					lines (N) and character font (F).DL=1: 8 bits;	
											DL=0: 4 bits. N=1: 2 lines; N=0: 1 lines. F=1:	
											5X11 dots; F=0: 5X7 dots.	
Set CG	0	0	0	1			A	20	ì		Set CG RAM address. CG RAM data is sent and	40 µ S
RAM add											received after this setting.	
Set DD	0	0	1			A	١D	D			Set DD RAM address. DD RAM data is sent and	40 µ S
RAM Add											received after this setting.	
Read BF	0	1	В				AC	2	Read BUSY FLAG (BF) and the contents of the		0 µ S	
& Addr			F								address counter. BF=1: internal operation; BF=0:	
											can accept instruction.	
Write Data	1	0	۱	N	RI	T	Ξſ	DA	T	ł	Write data into DD RAM or CG RAM.	40
to RAM												μ <b>S</b> **
Read Data	1	0		R	ΕA	١D	D	A	TΑ		Read data from DD RAM or CG RAM.	40
from RAM												μ <b>S**</b>

#### **10. INITIALIZATION BY INSTRUCTION**



4-bits Power On Wait for more than 15 mS after Vdd rises to 4.5V RS R/W DB7 DB6 DB5 DB4 0 0 0 0 1 1 Function set: DL=1,8 bit interface data. ΊĻ Wait for more than 4.1 Ms RS R/W DB7 DB6 DB5 DB4 0 0 0 0 1 1 DL=1,8 bit interface data Wait for more than 0.1 Ms RS R/W DB7 DB6 DB5 DB4 0 0 0 0 1 0 DL=0,4 bit interface data RS R/W DB7 DB6 DB5 DB4 0 0 0 0 1 0 0 0 N F X X Function set: DL=0,4 bit interface data RS R/W DB7 DB6 DB5 DB4 0 0 0 0 0 0 0 1 0 0 0 Display Off ٦Ļ RS R/W DB7 DB6 DB5 DB4 0 0 0 0 0 0 0 0 0 0 1 Function set: DL=0.4 bit interface data RS R/W DB7 DB6 DB5 DB4 0 0 0 0 0 0 0 0 0 1 I/D S Entry mode set END OF INITIALIZATION

## 11. SOFTWARE EXAMPLES

8-BIT OPERA		N	8 cl	lard	icie	18 2	Λ <i>L</i>	11110	55			I
Function	RS	RV	V D7	D6	D5	D4	D3	D2	D1	D0	DISPLAY	DESCRIPTION
Power on delay												Initialization. No display appears.
Function set	0	0	0	0	1	1	0	0	Х	Х		Sets 8-bit operation, 2-line display and 5*7 dots character font.
Display OFF	0	0	0	0	0	0	1	0	0	0		Turn off display.
Display ON	0	0	0	0	0	0	1	1	1	0		Turn on display and cursor.
Entry Mode set	0	0	0	0	0	0	0	1	1	0		Set mode to increment the address by one and to shift the cursor to the right, at the time of write to the DD/CG RAM. Display is not shifted.
Write data to CG/DD RAM	1	0	0	1	0	0	1	1	1	1	<u>0</u>	Write "O". Cursor incremented by one and shift to right.
Write data to CG/DD RAM	1	0	0	1	0	1	0	0	1	0	<u>OR</u>	Write "R". Cursor incremented by one and shift to right
Write data to CG/DD RAM						•					ORIENT	Write "I" "E" "N" "T".
Set DDRAM address	0	0	1	1	0	0	0	0	0	0	ORIENT	Set RAM address so that the cursor is positioned at the head of the Second line
Write data to CG/DD RAM											<u>ORIENT</u>	Write "D" "S".
Cursor or display shift	0	0	0	0	0	1	0	0	Х	Х	ORIENT DS	Shift only the cursor position to the left.
Write data to CG/DD RAM					•	•	•				ORIENT DISPLAY	Write "I" "S" "P" "L" "A" "Y"

#### 8-BIT OPERATION 8 characters X 2 lines



Function	RS	RW	′ D7	D6	D5	D4	Display	Description
power on delay								Initialization. No display appears.
Function set	0	0	0	0	1	0		Sets to 4 -bit operation. In this case, operation is handled as 8-bits by initialization, and Only this instruction completes with one write.
Function set	0 0	0 0	0 0	0 0	1 X	0 X		Sets 4 -bit operation, 1-line display and 5*7 dot character font. (number of display lines and character fonts cannot be changed hence after.)
Display ON/OFF Control	0	0 0	0 1	0 1	Ũ	0 0	_	Turn on display and cursor.
Entry Mode Set	0 0	0 0	0 0	0 1	Ũ	0 0	_	Turn on display and cursor.
Write data to CG/DD/ARM	1 1		0 1	1 1	-	0 1		Write "O". Cursor incremented by one and shift to right.
						sam	e as 8-bit op	peration

#### 4-bit operation (4-bits 1 line)



# 12.Quality units

#### 12.1 Purpose

This standard for quality assurance should define the quality of LCD module products to customer by EASTERNTIONIC LCD GROUP.

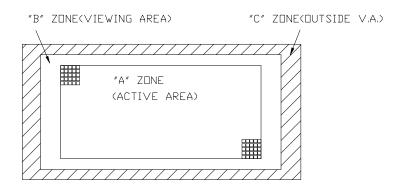
12.2 Scope

This document defines general provisions as well as inspection standards for LCD module supplied by EASTERNTIONIC LCD GROUP, except for those with special requirements from customer.

### 12.3 Definition

#### 12.3.1 Definition of area

- A Zone: Active area.
- B Zone: Viewing area
- C Zone: Outside viewing area.



### 12.3.2 Definition of size

Large size(L): 1~6 pcs LCD screens are cut out of from each 14"×16" mother glass. Middle size(M): 7~50 pcs LCD screens are cut out of from each 14"×16" mother glass.

Small size(S): more than 50 pcs LCD screens are cut out of from each  $14" \times 16"$  mother glass.

12.4 Quality Specification

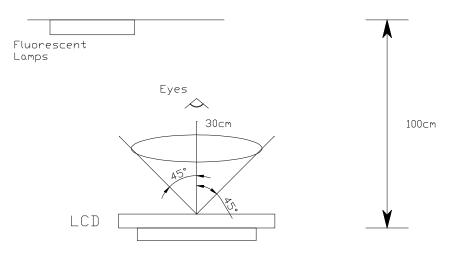
12.4.1 Conditions of Cosmetic Inspection

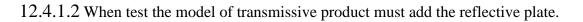
12.4.1 Test should be conducted under the following conditions:

Ambient temperature :22 $\pm$ 5°C. Ambient humidity: 65 $\pm$ 20%RH Ambient Luminance: 40-watt fluorescent lamp.



An appearance test should be conducted by human sight at approximately 30 cm distance from the LCD module under fluorescent light. Distance between LCD and fluorescent lamps should be 100 cm or more. Viewing direction for inspection is  $45^{\circ}$  from vertical against LCD.





# 12.4.2 Sampling plan

Unless otherwise agreed in writing, the sampling inspection shall be applied to the incoming inspection of customer.

- Lot size: Quantity of shipment lot per model
- Sampling type: Normal inspection, single sampling
- Sampling Level: Level II
- Sampling table: GB/T2828.1.1(GB-national standard of China)

12.4.3 Classification of defects and Acceptable quality level

Defects and classified as either a major or minor defect defined as bellows:

- Major defect: It is a defect that is likely to result in failure or to reduce materially the usability of the product for the intended function.

- Minor defect: It is a defect that will not result in functioning problem with deviation calssifiec.

The AQL for major and minor defects is defined as follows:

Partition	Definition	AQL
Major defect	Functional defective as product	0.4
Minor defect	Satisfy all functions as product but not satisfy cosmetic standard	1.0

# 12.4.4 Applicable instrument

- LCD module tester
- Multimeter
- Caliper
- Defect size filming standard

#### 12.4.5 Inspection quality criterion

### 12.4.5.1 LCD panel part

#### The inspection specification as following list:

Classify	Item	Description of		on criterion	Drawing
		defects			specification
Major	1.Non-display	Product no	Not	accept	
defect		function			
	2.LCD with	Difference in	Not	accept	
	wrong view	Spec.			
	direction`				
	3.Segment	Part or all pattern	Not	accept	
	missing	do not light up			
	4.Occur high	Current exceed	Not	accept	
	current	designed value			
	5. LC leakage	LC does not	Not	accept	
		fulfill the glass			
		cell			
	6.Deviation	LCM Dimension	According to dimensions		
	from drawing	difference from	noted in the	e specification	
		drawing and over			
		tolerance			
	7.Wrong type	Wrong polarizer	Not	accept	
	applied	attachment		-	
		Pin attached	Not	accept	
		wrong type			
		applied			
	8.Incorrect	Pin attached	Not	accept	
	pins quality	wrong quantity			
		applied		1	
Minor	9.Pattern	Segment fatter or	Dimension	Acceptable	_⇒ <sup>A</sup> ⊭-
defect	deformation	smaller	(mm)	number	
			A≤0.1	Not count	
				(Should not be	
				connected to	
				next dot)	



	and foreign matters	on LCD(non-display )	<ul> <li>1.A zone</li> <li>- Large size LCD</li> <li>Accept if can't find at distance and will not enla under electronic test:</li> </ul>	
	11.Blemishes	Black spot/dust	Positive panel:	¥
Minor defect	10.Pinholes	Black spot/white spot at activated state	less (Should not connected next dot) $B \le 0.10$ Not count1. large size LCD Accept if can't be found 1m distance and will not enlarge under electronic 2. Middle size LCD Diameter(mm) Accept Q' $\Phi \le 0.15$ Not count $0.15 < \Phi \le 0.25$ $3$ $0.25 < \Phi \le 0.35$ $1$ $\Phi > 0.35$ $0$ 3. Small size LCD Diameter(mm) Accept Q' $\Phi \le 0.15$ Not count $0.15 < \Phi \le 0.25$ 	to at at ot test TY $\Phi = (X+Y)/2$ ern: of or one et in
			0.10 <a≤0.15 1="" dot(<br="" pc="">segment)or 2 pcs / cel</a≤0.15>	less

1
-Middle size LCD
Diameter(mm) Accept QTY
$\Phi \le 0.15$ Not count
$0.15 < \Phi \le 0.25$ 3
$0.25 < \Phi \le 0.35$ 1
$\Phi > 0.35$ 0
-Small size LCD
Diameter(mm) Accept QTY
$\Phi \leq$ 0.15 Not count
$0.15 < \Phi \le 0.25$ 2
$0.25 < \Phi \le 0.30$ 1
$\Phi > 0.30$ 0
2.B zone
1.5 times of acceptable
largest diameter size of Zone
A
3.C zone
Notcount.
Negative panel:
1. A zone
-Large size LCD
Diameter(mm) Accept QTY
$\Phi \leq 0.15$ Not count
$0.15 < \Phi \le 0.30$ 4
$0.30 < \Phi \le 0.50$ 1
$\Phi > 0.50$ 0
-Middle&small size LCD
Diameter(mm) Accept QTY
$\Phi \leq 0.15$ Not count
$0.15 < \Phi \le 0.25$ 3
$\Phi > 0.25$ 0
2. B zone
1.5 times of acceptable
largest diameter size of Zone
A
3.C zone
No count
The nearest diatance allowed
between two black spot is
20mm
20mm

12.Black	Scratch on glass	Positive panel:	
lines and	or polarizer	1.A zone	
	surface.And		
scratches		- Large size LCD	
	foreign linear	Accept if can't find at 1m	
	matters in LCD	distance and will not enlarge	
		under electronic test.	
		-Middle size LCD	
		Diameter(mm) Accept QTY	
		$W \le 0.02$ Not count	
		$0.02 < W \le 0.03, L \le 4$ 2	
		$0.03{<}~W{\leq}$ 0.05,L ${\leq}3$ $\qquad$ 2	
		$0.02 < W \le 0.03, L > 4 0$	
		$0.03 < W \le 0.05, L > 3 0$	
		W>0.05 As the spot criteria.	
		-Small size LCD	
		Diameter(mm) Accept QTY	
		$W \le 0.02$ Not count	
		$0.02 < W \le 0.03, L \le 4$ 2	
		$0.03 < W \le 0.05, L \le 2$ 1	
		$0.02 < W \le 0.03, L > 4$ 0	
		$0.03 < W \le 0.05, L > 2$ 0	
		W>0.05 As the spot criteria.	
		w > 0.05 His the spot enterna.	
		2.B zone	
		1.5 times of acceptable largest	
		diameter size of Zone A	
		3.C zone	
		Notcount.	
		rocount.	
		Negative panel:	
		1. A zone	
		-Large size LCD	
		Diameter(mm) Accept QTY	
		$W \le 0.02$ Not count	
		$0.02 < W \le 0.03, L \le 5$ 3	
		$0.03 < W \le 0.05, L \le 4$ 2	
		$0.02 < W \le 0.03, L > 5$ 0	
		$0.03 < W \le 0.05, L > 4 = 0$	
		W>0.05 As the spot criteria.	
		-Middle size LCD	

			Diameter(mm) Accept QTY $W \le 0.02$ Not count $0.02 < W \le 0.03, L \le 4$ 2 $0.03 < W \le 0.05, L \le 2$ 2 $0.02 < W \le 0.03, L > 3$ 0 $0.03 < W \le 0.05, L > 2$ 0 W > 0.05 As the spot criteria. -Small size LCD Diameter(mm) Accept QTY $W \le 0.02$ Not count $0.02 < W \le 0.03, L \le 3$ 2 $0.03 < W \le 0.05, L \le 3$ 1 $0.02 < W \le 0.03, L > 3$ 0 $0.03 < W \le 0.05, L > 2$ 0 W > 0.05 As the spot criteria. <b>2. B zone</b> 1.5 times of acceptable largest diameter size of Zone A <b>3.C zone</b> Not count The nearest diatance allowed between two defects is 20mm	
Mintor defect	13. Scratch on PI coating	PI coating scratched	The visible scratch of A zone can not be accepted at 30cm view distance.	
Mintor defect	14. Rainbow	Arches,circular or parallel colorful spread	According to the limit specimen	
Mintor defect	15. Bubbles or wrinkles in polarizer	Bubbles or wrinkles between polarizer and glass	A zone:The visible defect can not be accepted at 30cm view distance. B zone: Not count	
Mintor defect	16. Position of polarzer attachment	Wrong polarizer attachment in position or dimension	Polarizer protruding from edge of glass and exceeding/within the maximum external dimension of LCD	



							[
Mintor	17. Ink	17.1 Ink	Not acce	pt			
defect	printing	line/pattern					
	defect	broken					
		17.2 Ink	Accept i	f the thick	or thir	n part is	
		pattern/line	less than	equal to	25% s	segment	
		jagged	width, o	r accordin	ng to th	ne limit	
			specimer		C		
		17.3 Light	÷	activated	with	current	
		leakage	white lig	ht appears	in the	position	
		8-	_	le or scra			
				misalignn			
				hole spec		-	
			to the ph	more spee	meanor		
		17.4 Ink printing	Reject if	the thick	or thin	in more	
		pattern/line	than $1/2^{V}$				
		uneven		hen W1-V	V2<1/3	N	
			100000			•	
Mintor	18. Pin defect	18.1 Corrosion	Pin	incomin	g	defect:	`
defect		or foreign		,damage(i	0		
		material on		damaged)			
		terminal legs		om glass			
		terminar legs	legs.Not	-	, 01 (	erminur	
		18.2 Pin	-	ng to the s	pecifica	tion	
		deviation over	Accordin	ig to the s	peemea	lion	
Mintor	10 Chinned	tolerance 19.1 Chip in	0	b	0	accept	
	19. Chipped	-	a	U	с	-	
defect	glass on	lead contact	. 5	1		QTY	
	comer	area.	a≤5mm	b≤W	c≤T		
			L>5m			3	ITO
			m				
			a <l< td=""><td>b≤W</td><td>c≤T</td><td>3</td><td></td></l<>	b≤W	c≤T	3	
			L<5m				
			m				
		19.2 Others	Not exc				
			width of	seal	c≤T	3	
							k t



Mintor defect	20. Glass	chip on edge	a	b	с	accept QTY	
			a≤5mm	Not exceed 1/2 width of seal	c≤T	3	
Mintor	21. Clipped electrode pad	21.1Glass chip on ITO edge	a	b	c	accept QTY	ITO
defect			a≤4mm (and not exceed 4 ITO termina 1	b≤W/4	c≤T	3	
		21.2 Glass chip on ITO back	а	b	с	accept QTY	Q > b
			a≤5mm	b≤W/3	c≤T	3	V V V
Mintor defect	22. Mechanical	Extended crack inspector shall	b		accept QTY		
	damage	attempt to remove the chip with tweezers,re-eval	b≤W/4	2			
		uate if the remaining defect is still a crack or a chip					
Mintor defect	23.Gla	ass cracks	Not acce	pt			
	nimum space be TY in total:	etween any 2 defec	rt) should	l more	than 20m	m, and max. allowed	

Large size LCD: Zone A $\leq$  5/unit, Zone B $\leq$  5/unit;

Middle size LCD: Zone A $\leq$  3/unit, Zone B $\leq$  3/unit;

Small size LCD: Zone A $\leq 2$ /unit, Zone B $\leq 2$ /unit;

# 12.4.5.2 Other part

NO.	Items	Criterion of defects		
1	Backlight	<ol> <li>Lumination source flickers.</li> <li>Using spot, lines and contamination standard of LCD to judge the spots or scratches defect on backlight.</li> </ol>		
		3. Not allow unlighted on backlight.		
		4. Colour and luminance of backlight should correspond it specification.		
2	PCB,COB	PCB,COB 1.COB seal may not have pinholes larger than0.2mm contamination.		
		2.COB seal surface may not have pinholes through to the IC.	Minor	
		3. The height of COB should not exceed the height indicated in the assembly diagram.	Major	
	4. Beyond 2mm of the seal area, there may not have sea on the PCB.		Minor	
		5.No oxidation or contamination on PCB connector.		
		6.Parts on PCB should correspond the characteristic, and not		
		allow wrong parts, missing parts or additional parts.		
		7.The jumper on the PCB should correspond to the characteristic.	Minor	
		8.The solder which gets on bezel,LED pad,zebra pad or screw hole pad should be smoothed down.	Major	
		1. No unmelted solder pastes on the PCB.	Minor	
3	Soldering	2. No cold solder joints, solder connection missing, oxidation of solder.	Minor	
		3. No short circuits in components on PCB.	Minor	
4	General Appearance	1. No oxidation, contamination, curves, cracks or bends on interface Pin of TCP.	Minor	
		2. No solder residue or solder balls on product.	Minor	
		3. The IC on TCP may not be damaged.	Major	
		4. The residual rosin or tin oil of soldering(component or chip component) is not turned into brown or black colour.	Minor	
		5. Packing method correspond the specification.	Major	
		6. Dimension and structure correspond the specification sheet.	Major	
		7. No dirt and break on the heat seal.	Major	



# 12.5 Reliability

Item	Condition		Criterion			
High temperature operation	$+70^{\circ}\text{C}\pm2^{\circ}\text{C}$ , 8 hours					
Low temperature	$-20^{\circ}\text{C}\pm 2^{\circ}\text{C}$ , 8 hours		1.Total current			
operation		consumption				
Humidity	Operation	$40^{\circ}C \pm 2^{\circ}C, 93\% \pm 2\%$ RH,8	should be below			
		hours	double of initial			
	Storage	$40 \degree C \pm 2 \degree C$ ,93% $\pm 2\%$ RH,	value.			
		24 hours	2.Cosmetic defects			
High temperature	$+80^{\circ}\text{C}\pm2^{\circ}\text{C}$ , 10 hours		should not be			
storage			happened			
Low temperature	$-30^{\circ}\text{C} \pm 2^{\circ}\text{C}$ , 10 h					
storage						
Thermal shock	-20°C∼+70°C					
storage	60min~60min, 5 c					
Vibration test	Amplitude:0.7~1.0					
	in each direction(X					
Shock test	To be measured aft					
	80cm high on the c					
	state.(weight≥15k					
	Weight < 15Kg, dro					
	F	Dropping method corner dropping				
	E	D A corner: once				
	G	Edge dropping				
	В	A B,C,D edge: once				
	60/8	BOcm Face dropping E,F,G face: once				
	· · · · · · · · · · · · · · · · · · ·					
Remark: The function test shall be conducted after 4 hours storage at the normal						
temperature and humidity after removed from the test chamber.						

The LCD module shall not fail the following reliability test.

#### 13. PRECAUTION FOR USING LCM

#### 1. LIQUID CRYSTAL DISPLAY (LCD)

LCD is made up of glass, organic sealant, organic fluid, and polymer based polarizers. The following precautions should be taken when handing,

(1). Keep the temperature within range of use and storage. Excessive temperature and humidity could cause polarization degredation, polarizer peel off or bubble.

(2). Do not contact the exposed polarizers with anything harder than an HB pencil lead. To clean dust off the display surface. Wipe gently with cotton. Chamois or other soft material soaked in petroleum benzin.

(3). Wipe off saliva or water drops immediately. Contact with water over a long period of time may cause polarizer deformation or color fading, while an active LCD with water condensation on its surface will cause corrosion of ITO electrodes.

(4). Glass can be easily chipped or cracked from rough handing. especially at corners and edges.

(5). Do not drive LCD with DC voltage.

#### 2. Liquid Crystal Display Modules

2.1 Mechanical Considerations

LCM are assembled and adjusted with a high degree of precision. Avoid excessive shocks and do not make any alterations or modifications. The following should be noted.

(1). Do not tamper in any way with the tabs on the tabs on the metal frame.

(2). Do not modify the PCB by drilling extra holes, changing its outline, moving its components or modifying its pattem.

(3). Do not touch the elastomer connector, especially insert an backlight panel (for example, EL).

(4). When mounting a LCM make sure that the PCB is not under any tress such as bending or twisting. Elastomer contacts are very delicate and missing pixels could result from slight dislocation of any of the elements.

(5). Avoid pressing on the metal bezel, otherwise the elastomer connector could be deformed and lose contact, resulting in missing pixels.

2.2. Static Electricity

LCM contains CMOS LSI's and the same precaution for such devices should apply, namely

(1). The operator should be grounded whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.

(2). The modules should be kept in antistatic bags or other containers resistant to static for storage.

(3). Only properly grounded soldering irons should be used.

(4). If an electric screwdriver is used, it should be well grounded and shielded from commutator sparks.

(5). The normal static prevention measures should be observed for work clothes and working benches; for the latter conductive (rubber) mat is recommended.

(6). Since dry air is inductive to statics, a relative humidity of 50-60\% is recommended.

2.3. Soldering

(1). Solder only to the I/O terminals.

(2). Use only soldering irons with proper grounding and no leakage.

(3). Soldering temperature: 280  $^\circ\!\mathrm{C}\pm10^\circ\!\mathrm{C}$ 

(4). Soldering time: 3 to 4 sec.

(5). Use eutectic solder with resin flux fill.

(6). If flux is used, the LCD surface should be covered to avoid flux spatters. Flux residue should be removed after wards.

2.4. Operation

(1). The viewing angle can be adjusted by varying the LCD driving voltage V0.

(2). Driving voltage should be kept within specified range; excess voltage shortens display life.

(3). Response time increases with decrease in temperature.

(4). Display may turn black or dark blue at temperatures above its operational range; this is (however not pressing on the viewing area) may cause the segments to appear "fractured".

(5). Mechanical disturbance during operation (such as pressing on the viewing area) nay cause the segments to appear "fractured".

2.5. Storage

If any fluid leaks out of a damaged glass cell, wash off any human part that comes into contact with soap and water. Never swallow the fluid. The toxicity is extremely low but caution should be exercised at all the time.

#### 2.6. Limited Warranty

Unless otherwise agreed between EASTERNTRONIC and customer, EASTERNTRONIC will replace or repair any of its LCD and LC, which is found to be defective electrically and visually when inspected in accordance with EASTERNTRONIC acceptance standards, for a period on one year from data of shipment. Confirmation of such date shall be based on freight The warranty liability documents. of EASTERNTRONIC is limited to repair and/or replacement on the terms set forth above EASTERNTRONIC will not responsible for any subsequent or consequential events.

12. Declaration of conformity regarding the limitation of dangerous substances

# 深圳易事通液晶显示模块有限公司

SHENZHEN EASTERNTRONIC LCM CO., LTD.

4F, B3 Building, FuYuan Industrial Zone, FuYong Town,

BaoAn District, ShenZhen, P.R. China

DECLARATION OF CONFORMITY REGARDING THE LIMITATION OF DANGEROUS SUBSTANCES

WE, SHENZHEN EASTERNTRONIC LCM CO., LTD,

Declare that the product of CS2004B-D-BSXTSWN-100 complies with: The directive 2002/95/EC Dated 2003/01/27 regarding the limitation of dangerous substances, in particular to clause 4 which forbids the use of the following elements:

•Lead

• Mercury

●Cadmium

•Hexavalant chromium

•Polybrominated biphenyls

●Polybrominated diphenylethers

And to the annex which points out the exempted implementations  $\Box$  To the directive 73/23/eec dated 1973/02/19 and the standard EN60335-1 regarding prohibition of following elements:

• Oils containing polychlorinated biphenyl

- Asbestos
- Radioactive substances

SHENZHEN EASTERNTRONIC LCM CO., LTD.

Issued on June 24, 2010

According with the proposal of Technical Adaption Committee(TAC) of a limit of 0.1% by weight for lead hexavalent chromium, mercury, PBBs and PBDRs and 0.01% by weight for Cadmium.